

# Bill of Materials

TI DESIGNS

TIDA-00478

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number
1	4	C1, C3, C4, C8	10uF	CAP, CERM, 10F, 6.3V, X7R, 10%, 0805	TDK	C2012X7R0J106K125AB
2	10	C2, C5, C6, C7, C11, C12, C14, C17, C18, C19	4.7uF	CAP, CERM, 4.7uF, 10V, X7R, 10%, 0805	TDK	C2012X7R1A475K125AC
3	3	C9, C21, C22	100nF	CAP, CERM, 100nF, 10V, X7R, 10%, 0805	Kemet	C0805C104K8RACTU
4	6	C10, C16, C23, C24, C25, C26	10uF	CAP, CERM, 10uF, 10V, X7R, 10%, 0805	TDK	C2012X7R1A106K125AC
5	1	C13	4.7uF	CAP, CERM, 4.7uF, 16V, X7R, 10%, 0805	TDK	C2012X7R1C475K125AE
6	1	C15	10uF	CAP, CERM, 10uF, 16V, X7R, 10%, 0805	Samsung	CL21B106KQNNNE
7	1	C20	1uF	CAP, CERM, 1uF, 10V, X7R, 10%, 0805	Samsung	CL21B105KPFNNNE
8	1	C28	47uF	CAP, CERM, 47uF, 10V, X5R, 20%, 0805	TDK	C2012X5R1A476M125AC
9	1	H1		USB2ANY	Texas Instruments	HPA665-001
10	4	H2, H3, H4, H5		Bumpon, Hemisphere, 0.44 X 0.20, Clear	3M	SJ-5303 (CLEAR)
11	2	J1, J2		Terminal Block, 6A, 3.5mm Pitch, 3-Pos, TH	On-Shore Technology	ED555/3DS
12	4	J3, J4, J5, J6		Terminal Block, 6A, 3.5mm Pitch, 4-Pos, TH	On-Shore Technology	ED555/4DS
13	1	J7	N2510-6002RB	Connector, Male Straight 2x5 pin, 100mil spacing, 4 Wall	3M	N2510-6002RB
14	4	JP1, JP3, JP4, JP5	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	Sullins	PEC03SAAN
15	1	JP2	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	Sullins	PEC02SAAN
16	4	L1, L2, L3, L4	1.5uH	Inductor, Shielded, Ferrite, 1.5uH, 2.8A, 0.09 ohm, SMD	TDK	SPM3012T-1R5M
17	2	L5, L6	10uH	Inductor, Multilayer, Ferrite, 10uH, 0.5A, 0.3 ohm, SMD	TDK	MLZ2012N100LT000
18	10	R1, R2, R4, R6, R9, R10, R12, R19, R20, R21	100k	RES, 100 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW0603100KFKEA
19	7	R3, R5, R7, R8, R11, R23, R24	0	RES, 0 ohm, 5%, 0.333W, 0805	Vishay-Dale	CRCW08050000Z0EAHP
20	1	R22	10	RES, 10, 5%, 0.25 W, 0603	Vishay-Dale	CRCW060310R0JNEAHP
21	2	R25, R26	4.75k	RES, 4.75 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW06034K75FKEA

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number
22	1	S1		Switch, Tactile, SPST-NO, 1VA, 32V, SMT	C&K Components	KT11P2JM34LFS
23	5	SH-J1, SH-J2, SH-J3, SH-J4, SH-J5	1x2	Shunt, 100mil, Flash Gold, Black	Sullins Connector Solutions	SPC02SYAN
24	2	TP1, TP2	Black	Test Point, Miniature, Black, TH	Keystone	5001
25	11	TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13	White	Test Point, Miniature, White, TH	Keystone	5002
26	1	U1		Power Management for FPGAs/SOCs, RSL0048B	Texas Instruments	TPS65218RSL
27	0	C27	470uF	CAP, ALUM, 470uF, 25V, +/-20%, SMD	Panasonic	EEE-1EA471UAP
28	0	C29, C30, C31, C32	68uF	CAP, TANT, 68uF, 16V, +/-20%, 250mOhm ESR, SMT	Kemet	T495C686M016ZTE250
29	0	FID1, FID2, FID3		Fiducial mark. There is nothing to buy or mount.	N/A	N/A
30	0	R13, R14, R15, R16, R17, R18	1.00k	RES, 1.00 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW06031K00FKEA

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